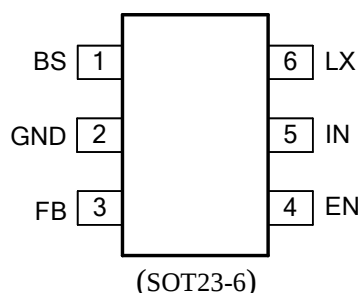






Pinout (top view)



Top Mark: My xyz(Device code: My, x=*year code*, y=*week code*, z= *lot number code*)

Pin Name	Pin Number	Pin Description
BS	1	Boot-strap pin. Supply high side gate driver. Decouple this pin to the LX pin with a 0.1 μ F ceramic capacitor.
GND	2	Ground pin.
FB	3	Output feedback pin. Connect this pin to the center point of the output resistor divider (as shown in Figure 1) to program the output voltage: $V_{OUT}=0.6 \times (1+R1/R2)$.
EN	4	Enable control. Pull high to turn on. Do not leave it floating.
IN	5	Input pin. Decouple this pin to the GND pin with at least a 1 μ F ceramic capacitor.
LX	6	Inductor pin. Connect this pin to the switching node of the inductor.

Function Block

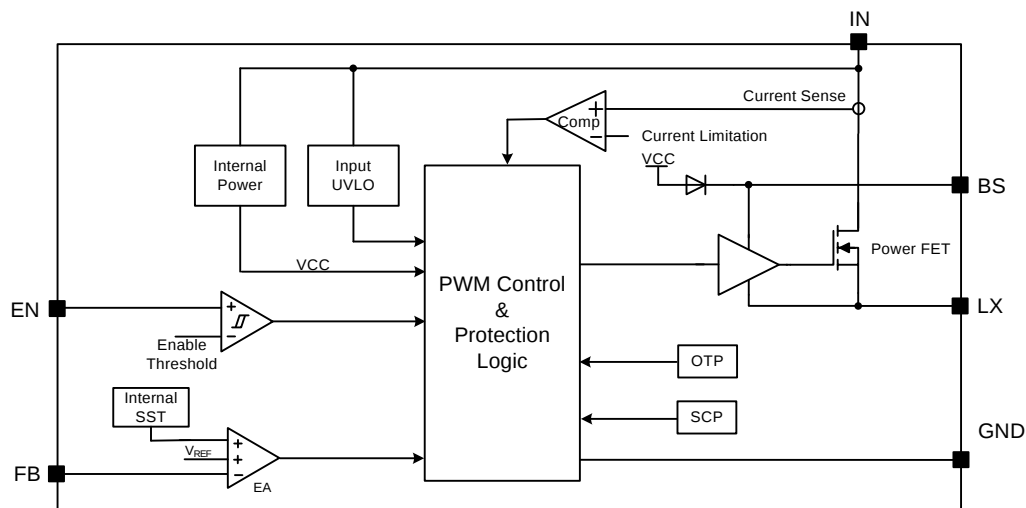


Figure3. Block Diagram



Absolute Maximum Ratings (Note 1)

Supply Input Voltage	-0.3V to 60V
BS-LX Voltage	-0.3V to 4V
FB, EN Voltage	-0.3V to $V_{IN} + 0.3V$
Power Dissipation, P_D @ $T_A = 25^\circ C$, SOT23-6	1W
Package Thermal Resistance (Note 2)	
θ_{JA}	100 $^\circ C/W$
θ_{JC}	25 $^\circ C/W$
Junction Temperature Range	-40 $^\circ C$ to 150 $^\circ C$
Lead Temperature (Soldering, 10 sec.)	260 $^\circ C$
Storage Temperature Range	-65 $^\circ C$ to 150 $^\circ C$
Dynamic LX Voltage in 10ns Duration	IN+3V to GND-5V

Recommended Operating Conditions (Note 3)

Supply Input Voltage	4.5V to 55V
Junction Temperature Range	-40 $^\circ C$ to 125 $^\circ C$
Ambient Temperature Range	-40 $^\circ C$ to 85 $^\circ C$



Electrical Characteristics

($V_{IN} = 20V$, $V_{OUT} = 12V$, $L = 6.8\mu H$, $C_{OUT} = 10\mu F$, $T_A = 25^\circ C$, $I_{OUT} = 0.1A$ unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage Range	V_{IN}		4.5		55	V
Quiescent Current	I_Q	LX not switching		150		μA
Shutdown Current	I_{SHDN}	EN=0		5	10	μA
Feedback Reference Voltage	V_{REF}		0.594	0.6	0.606	V
FB Input Current	I_{FB}	$V_{FB} = V_{IN}$	-50		50	nA
Power FET RON	$R_{DS(ON)}$			700		m Ω
Power FET Peak Current Limit	$I_{LIM, TOP}$		1.05		1.65	A
EN Rising Threshold	V_{ENH}		1.18	1.23	1.28	V
EN Falling Threshold	V_{ENL}		0.94	1	1.06	V
Input UVLO Threshold	V_{UVLO}				4.5	V
Switching Frequency	F_{SW}			1.2		MHz
Switching Frequency Accuracy			-20		20	% F_{SW}
Min ON Time	t_{ON}			100		ns
Min Off Time	t_{OFF}			80		ns
Soft-start Time	t_{SS}			1.4		ms
Thermal Shutdown Temperature	T_{SD}			150		$^\circ C$
Thermal Shutdown Hysteresis	T_{HYS}			15		$^\circ C$

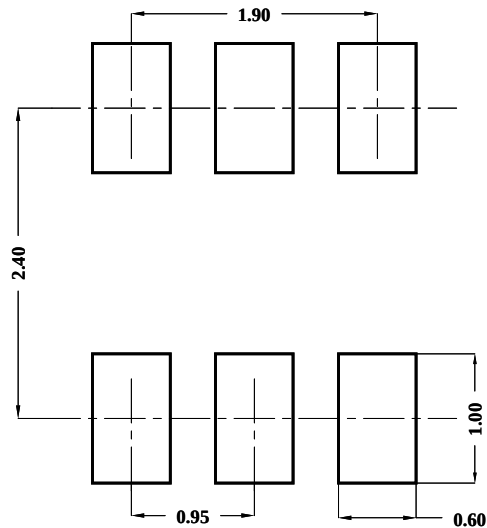
Note 1: Stresses beyond “Absolute Maximum Ratings” may cause permanent damage to the device. These are for stress ratings. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Note 2: θ_{JA} is measured in the natural convection at $T_A = 25^\circ C$ on a high effective thermal conductivity four-layer test board per JESD51-7. Pin 2 of SOT23-6 package is the case position for θ_{JC} measurement.

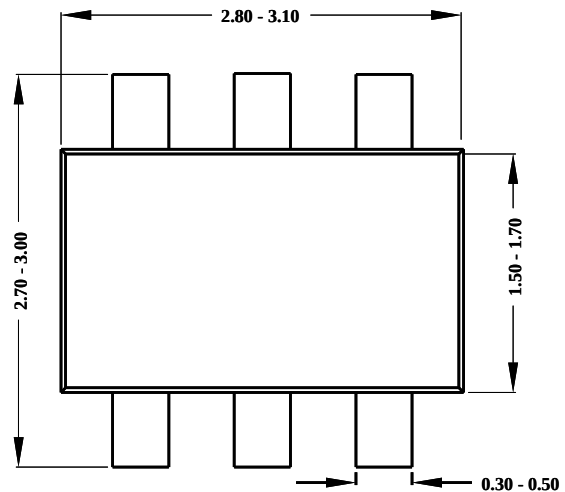
Note 3: The device is not guaranteed to function outside its operating conditions.



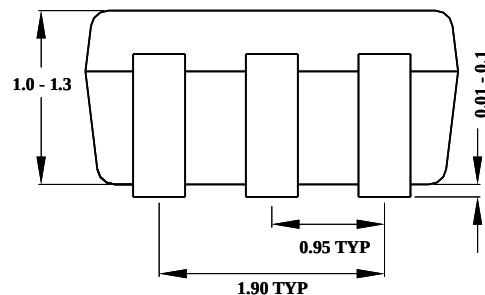
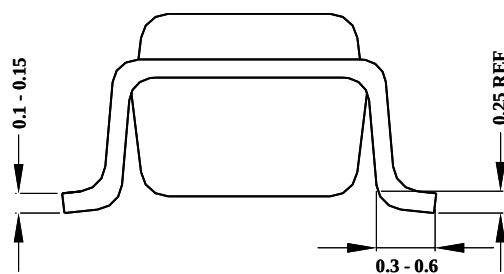
SOT23-6 Package Outline & PCB layout



Recommended Pad Layout



Top View



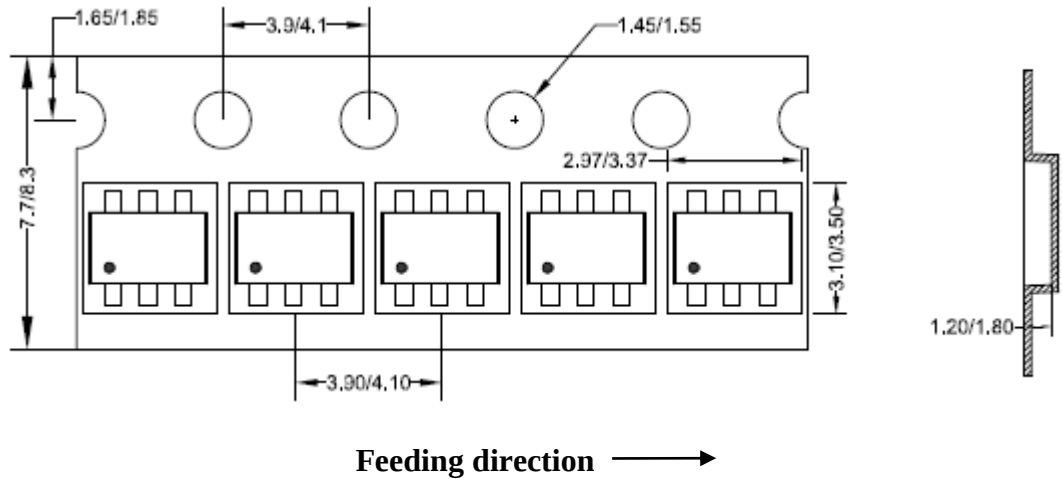
Notes: All dimension in millimeter and exclude mold flash & metal burr.



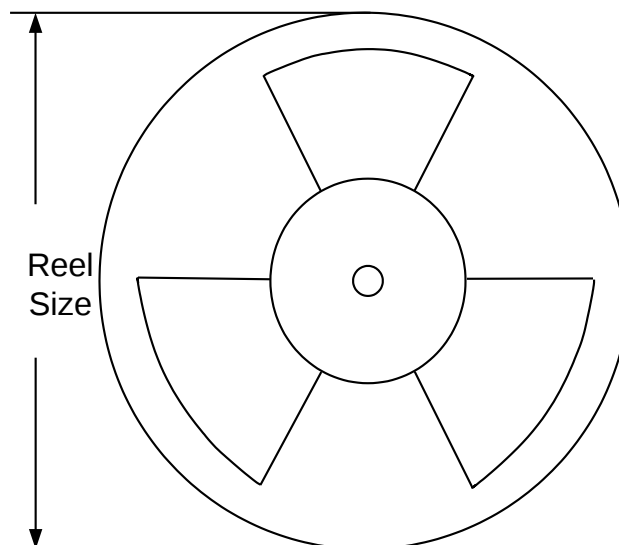
Taping & Reel Specification

1. Taping orientation

SOT23-6



2. Carrier Tape & Reel specification for packages



Package types	Tape width (mm)	Pocket pitch(mm)	Reel size (Inch)	Trailer length(mm)	Leader length (mm)	Qty per reel
SOT23-6	8	4	7"	280	160	3000

3. Others: NA